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# Part I: Semiconductor Lasers

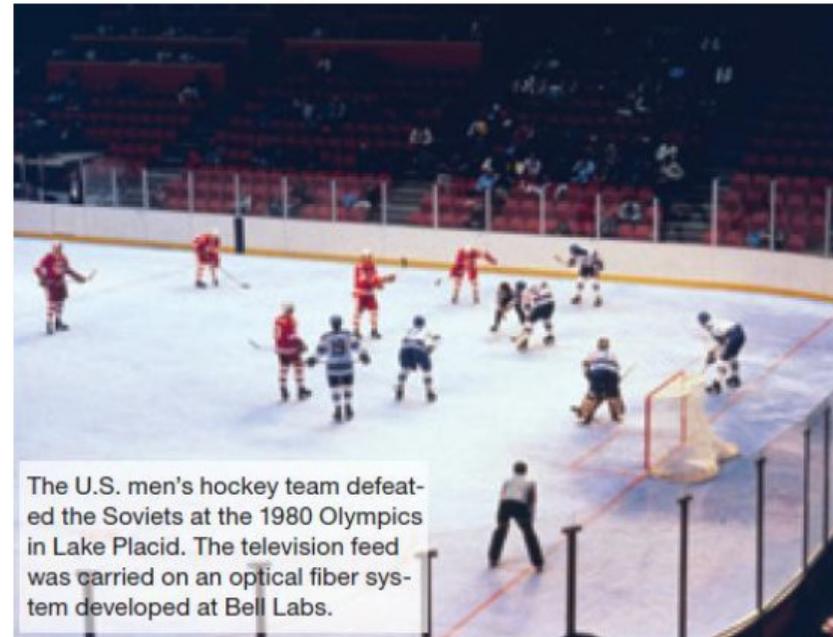


□ Semiconductor laser basics

# SCL history

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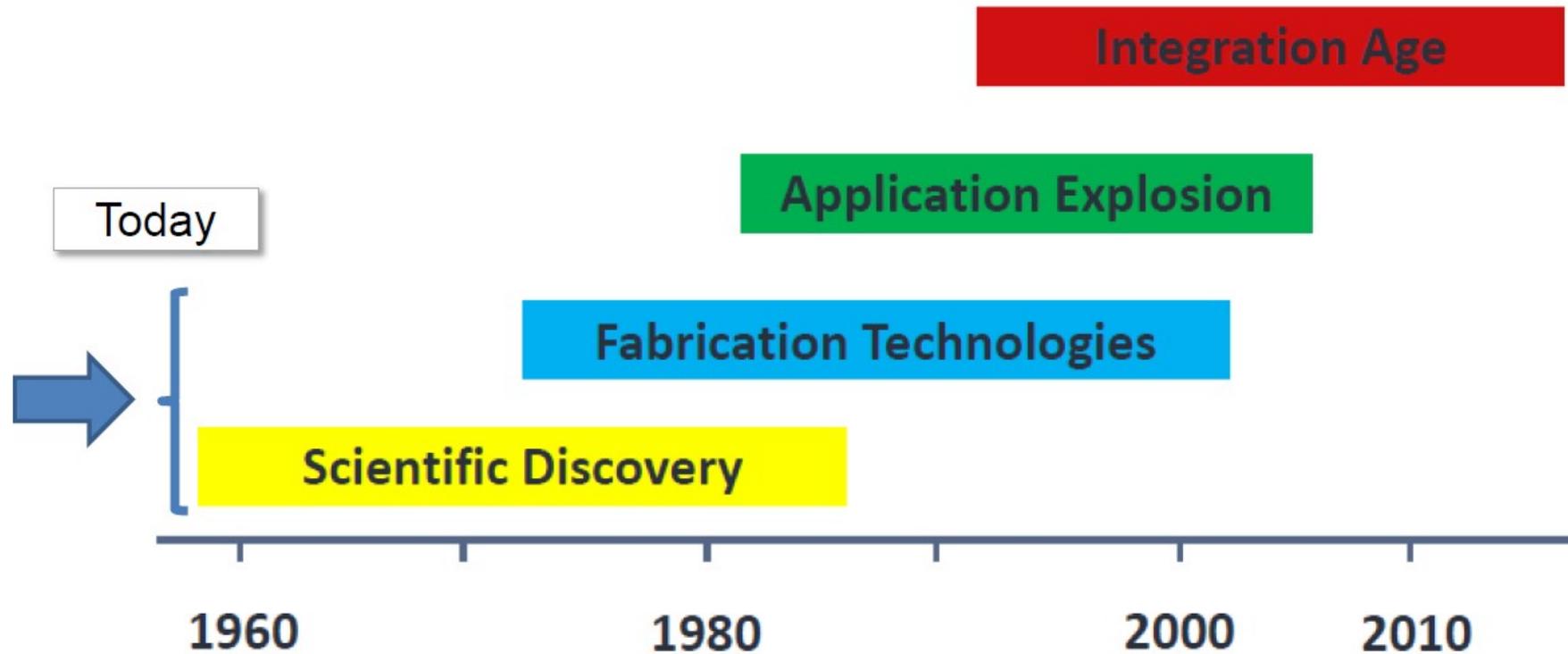
- First demonstration: **1962** (pulsed operation, cryogenic temperatures).
- cw RT emission: **1970**
- In the 60' & 70': SCLs where “**a solution looking for a problem**”.
- The first practical application: February **1980**, an optical fiber system was used to **broadcast TV** (Winter Olympics, Lake Placid, US).



Source: Optics & Photonics News May 2012

# Laser diode evolution

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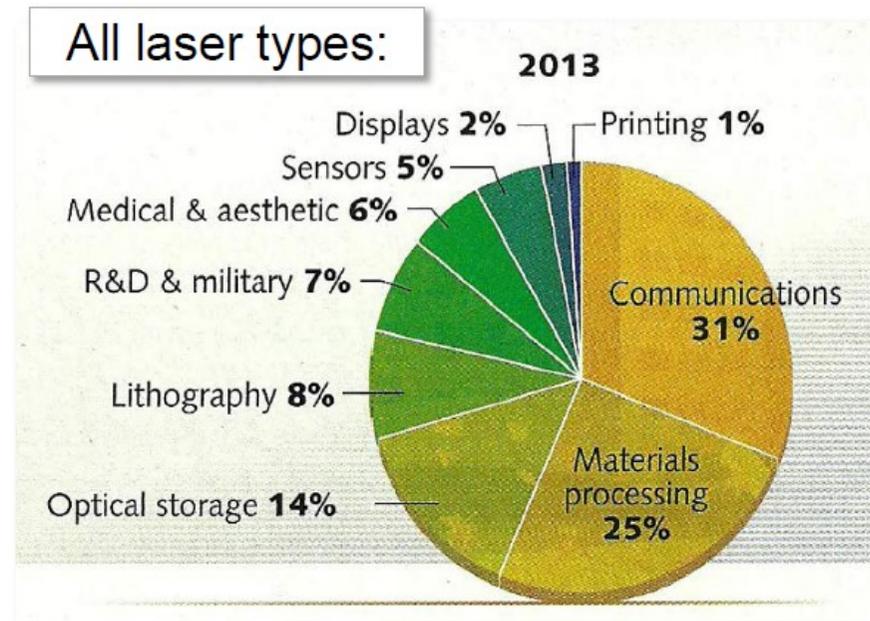
# Main applications

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- Optical fiber communications
- Optical storage

**No diode laser**

**⇒ No internet!**



- But diode lasers are also widely used in printers, scanners, sensors, pumping of solid-state lasers, etc.
- A dramatic reduction of the fabrication price made possible these applications

The diode laser in a computer mouse costs about 10 US cents

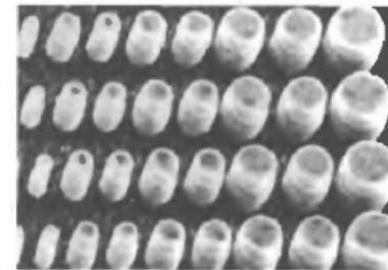


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# For telecom & IT applications

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- Diode lasers can be **modulated at high speeds**: fast response to high-frequency information-modulated currents.
- Semiconductor materials provide a **wide range of wavelengths**. In particular, in the low-loss and low-dispersion regions of optical fibers.
- Easy integration in 1D & 2D arrays.



VCSELs with diameters between 1 and 5  $\mu\text{m}$ . Adapted from Saleh and Teich

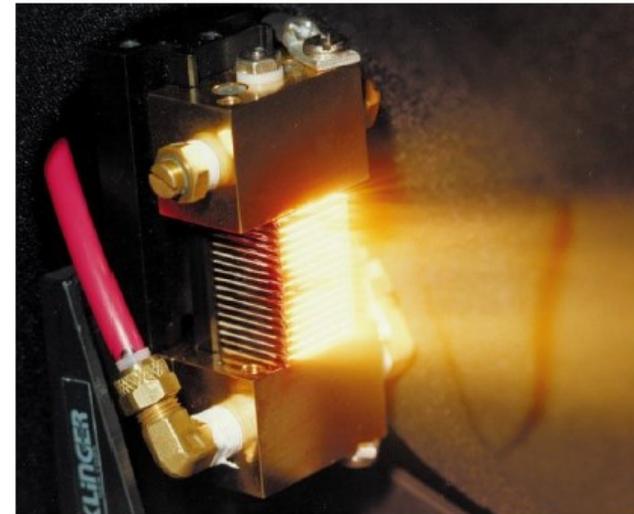


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# For high power applications

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- One laser diode produce  $> 1$  W power
- Diode lasers are used to pump **solid-state lasers**, such as the Nd:YAG. Laser diodes are tuned to the absorption band of the crystal providing efficient pumping.
- Also used to pump **Erbium Doped Fiber Amplifiers** (EDFAs), which are crucial for the amplification of signals in long distance fiber-optic links.



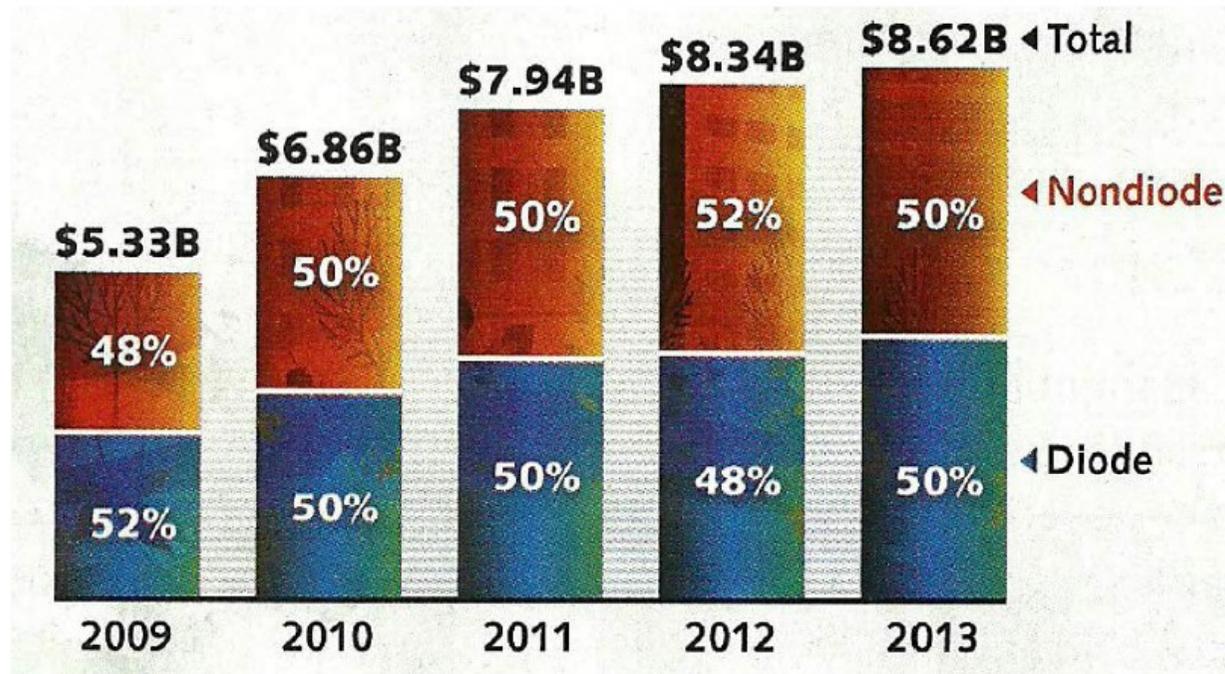
Source: Wikipedia



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# SCL market

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- They enable the development of key transformation technologies with **huge social impact**.

Source: Laserfocusworld.com

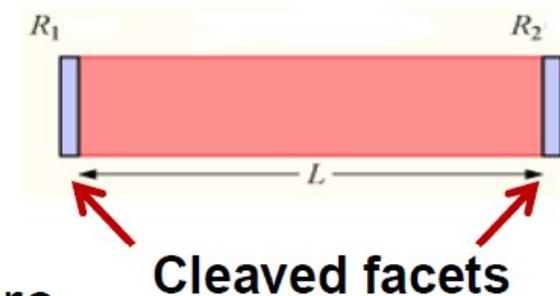


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# Why are SCL so successful?

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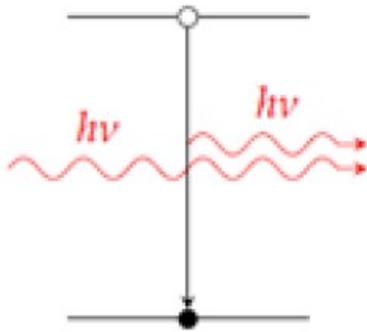
- The semiconductor medium has **huge gain** & do not require fragile enclosures or mirror alignment (the laser cavity is composed by the two facets of the semiconductor).
- **Low cost** fabrication because of existing semiconductor technology.
- Compared to other lasers, diode lasers are **very efficient** (nowadays 100% for the output photons with respect to the injected electrons).
- **Bright output** considering their **small size**.
- **Low threshold** current, **low energy consumption**.



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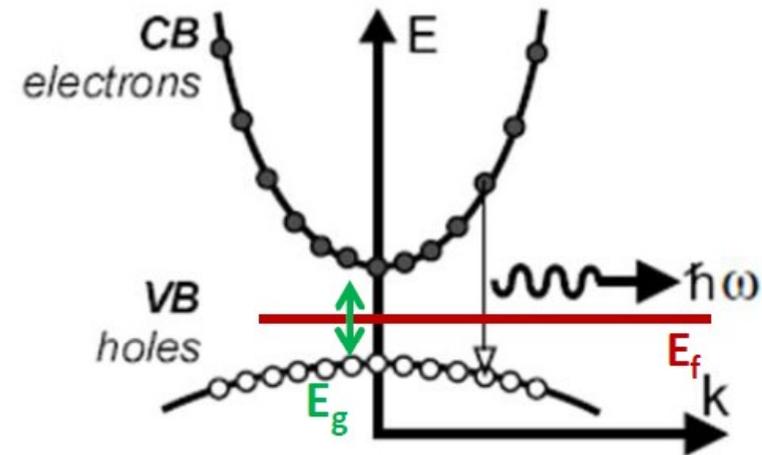
# Comparison with a 2-level system

In a 2-level system: **non interacting particles & individual energy levels**



A particle in an excited state decays emitting a photon

In a semiconductor: **electron/hole pairs & energy bands**



An **electron** in the CB and a **hole** in the VB recombine emitting a photon

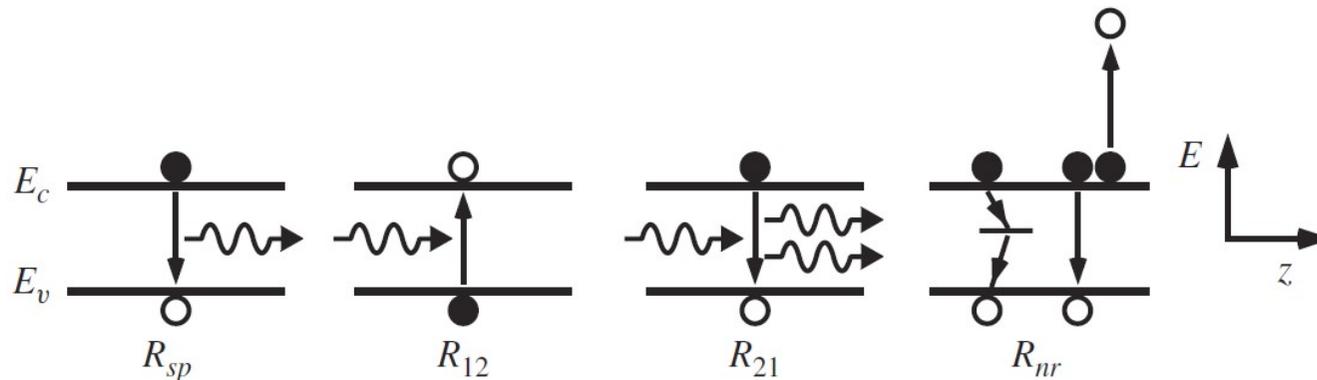
Conservation of momentum:  $p_e \approx p_h$  ( $p_{\text{photon}} \approx 0$ )  $\Rightarrow k_e \approx k_h$

$\Rightarrow$  Optical transitions are **vertical** in  $k$  space



# Electronic recombination/generation (R/G)

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## ❑ Spontaneous emission, (carrier R)

Incoherent, the rate  $R_{sp}$  is proportional to  $N^*P$

## ❑ Stimulated absorption (carrier G)

## ❑ Stimulated emission, coherent (carrier R)

Coherent, the net rate ( $R_{21}-R_{12}$ ) is proportional to  $N_p^*(N-N_{tr})$ ,  $R_{21}=R_{12}$  at transparency (**Gain is zero, in contrast to the threshold, gain=loss**).

## ❑ Nonradiative carrier R

Induced by defects, surfaces, and interfaces, interact with phonon, the rate proportional to  $N$ ;

Induced by Auger recombination, the energy is transferred to a third carrier, the rate proportional to  $N^3$ ;

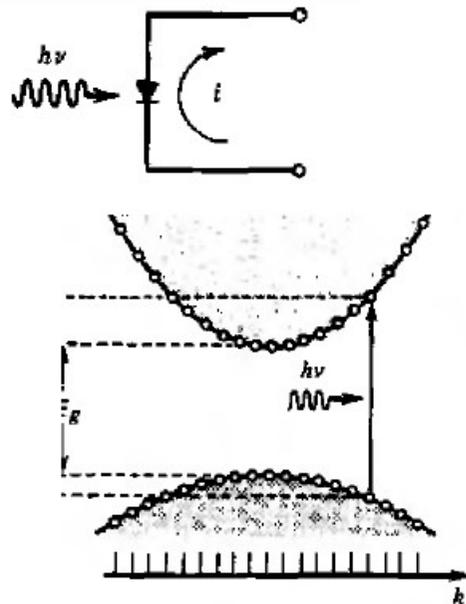


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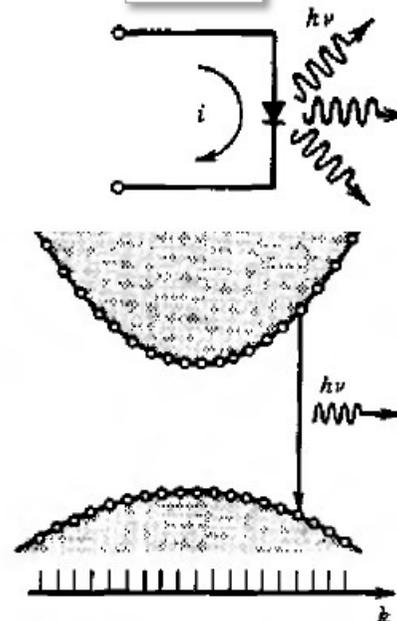
# Optical transitions

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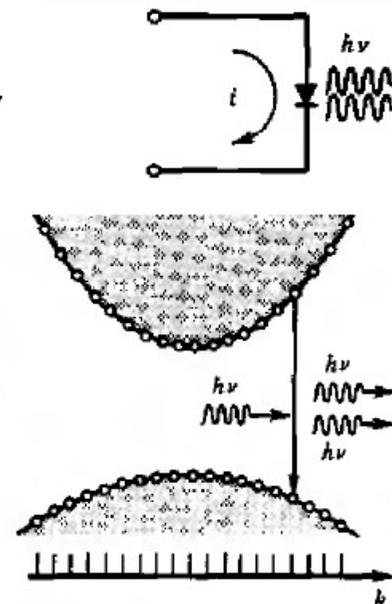
Photo-detectors



LEDs



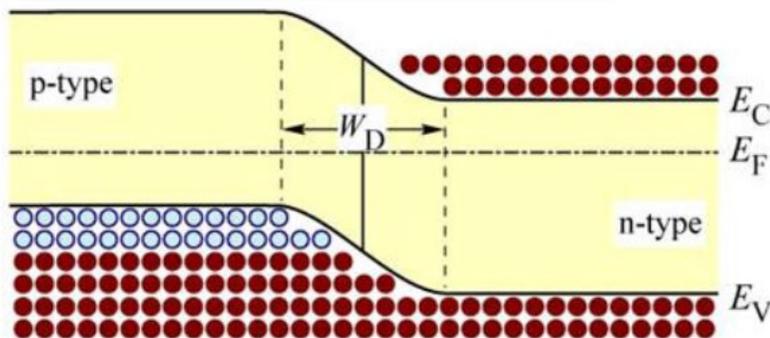
Diode lasers & amplifiers



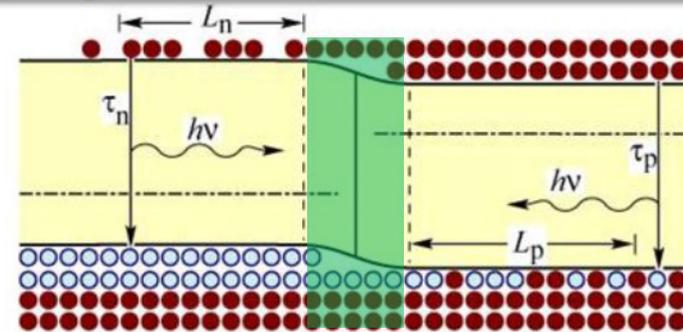
# Homostructure SCL (1<sup>st</sup> generation)

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p-n junction under 0 bias



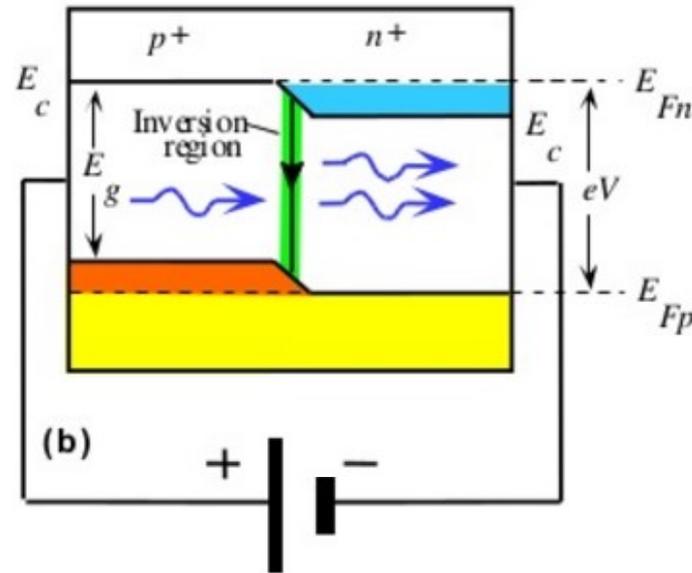
p-n junction under forward bias



- ❑ Forward bias reduces the potential barrier, and thus the electrons move to the p-doped side while holes move to the n-doped side.
- ❑ Meanwhile, there is an **active region** near the depletion layer that contains simultaneously holes and electrons (**in the same spatial region**).
- ❑ In the active region, **population inversion** is achieved.
- ❑ The population inversion leads to the stimulated emission.

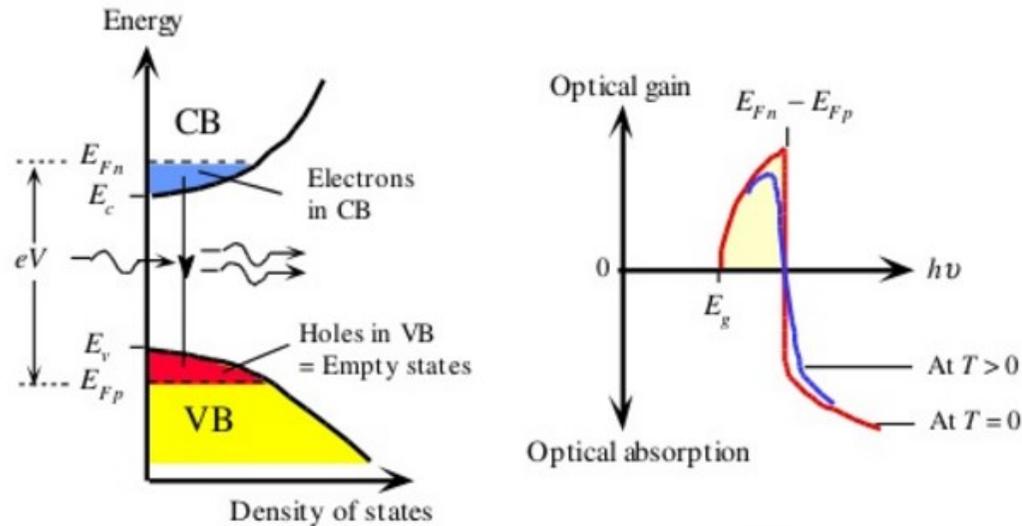
# Homostructure SCL

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- ❑ The forward bias voltage is greater than the band gap  $eV > E_g$ .
- ❑ The quasi-Fermi levels is pulled into the conduction band and the valence band.
- ❑ The separation between  $E_{Fn}$  and  $E_{Fp}$  equals to the applied potential energy.
- ❑ The built-in potential barrier becomes almost zero.

# Homostructure SCL



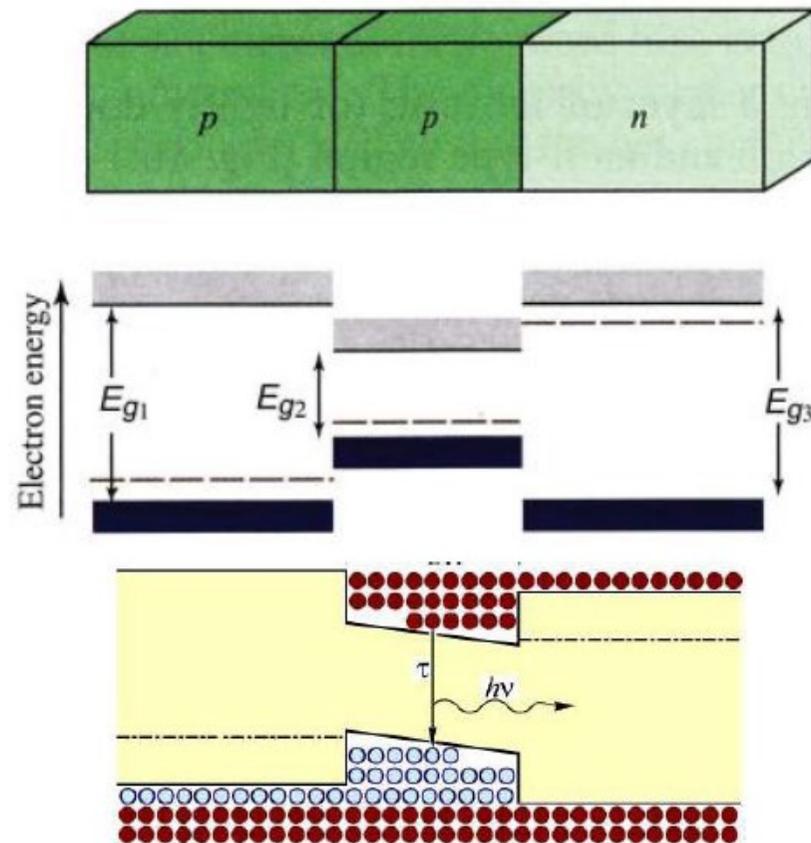
- ❑ For  $E_g < \Delta E < E_{Fn} - E_{Fp}$ , the electron density in the conduction band  $N_c$  is more than that in the valence band  $N_v$ , the population inversion  $\Delta N = N_c - N_v > 0$ , the gain is positive.
- ❑ For  $\Delta E = E_{Fn} - E_{Fp}$ , the electron density  $N_c = N_v$ , so  $\Delta N = 0$ , the gain is zero.
- ❑ For  $\Delta E > E_{Fn} - E_{Fp}$ , the electron density  $N_c < N_v$ , so  $\Delta N < 0$ , the gain is negative (absorption).



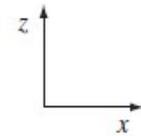
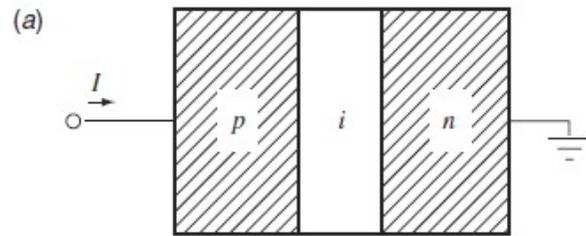
# Double heterostructure SCL (2<sup>nd</sup> generation)

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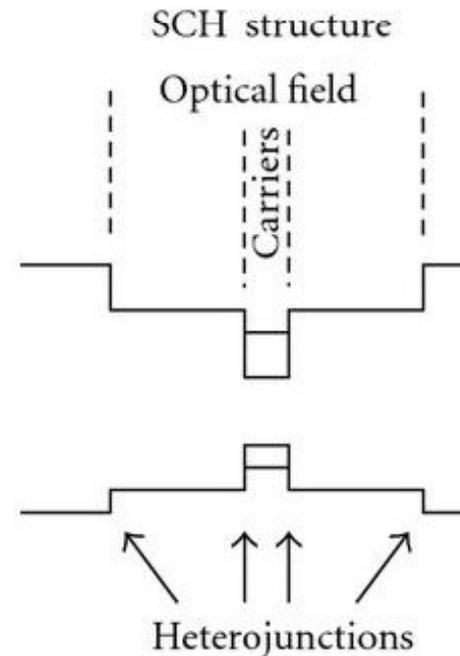
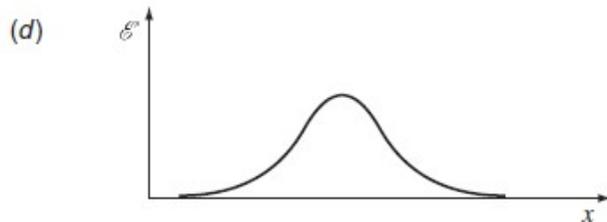
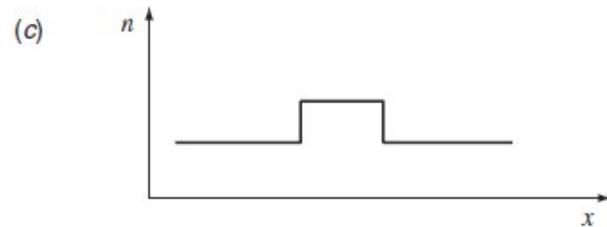
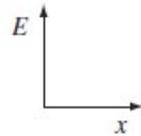
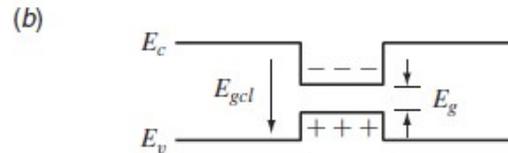
- The double heterostructure confines carriers in the active region, and thus improves the interaction efficiency between electrons and holes.



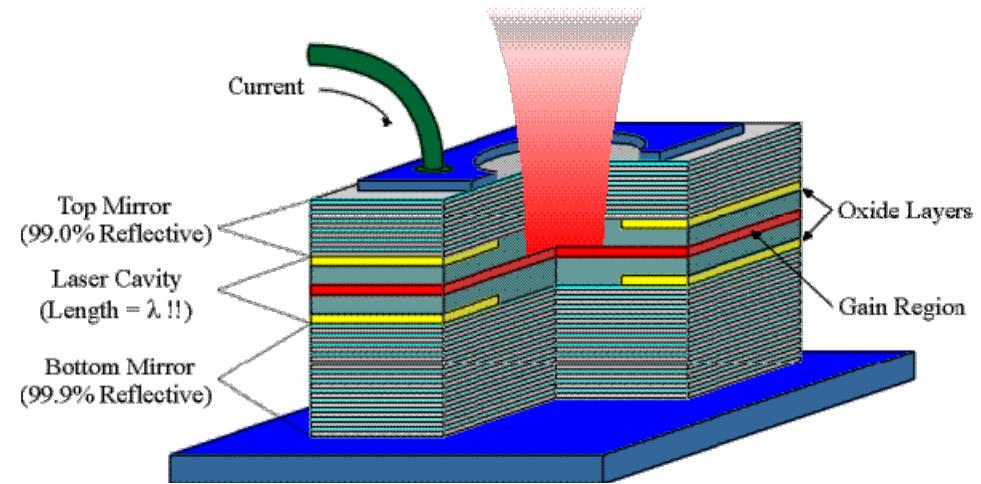
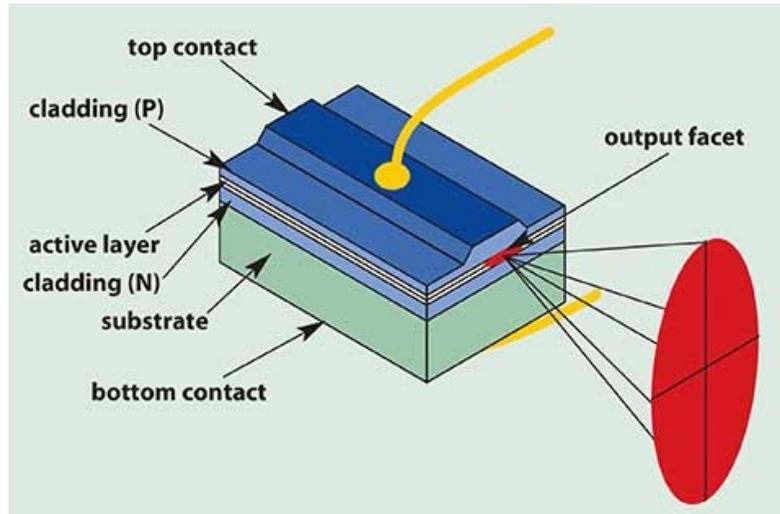
# Double heterostructure SCL



- ❑ The DH forms transverse confinement for both carriers and photons.
- ❑ The cleaved facets act as the mirrors ( $R=30\%$ ).
- ❑ The in-plane waveguide and the perpendicular mirrors form the resonant cavity.

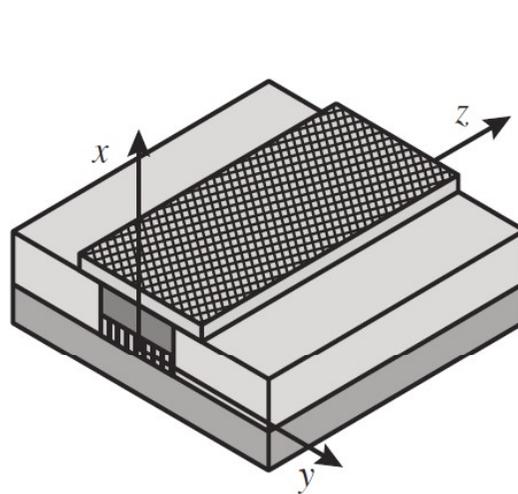


- ❑ In the separate confinement heterostructure (SCH), a thin well (10 nm) confines the carriers, while a separate confinement region confines the photons.

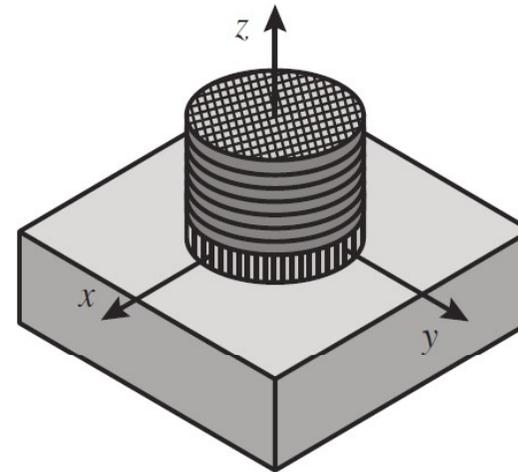


- ❑ Edge emitting laser: the light beam is parallel to the active region. The cavity mirror is formed by the cleaved facet.
- ❑ Vertical cavity surface emitting laser (VCSEL): the light beam is perpendicular to the active region. The mirror is formed by a multilayer reflective stack.

- ❑ Practical laser must emit light in a narrow beam, so lateral patterning of the active region is necessary. The lateral ( $y$ ) dimension is on the order of a few microns.



In-Plane



VCSEL

- ❑ The optical waveguide is sufficiently narrow to support only a single lateral mode, but sufficiently wide to support a relatively small diffraction angle, for coupling with optical fibers.
- ❑ For VCSELs, multimode (lateral) is desirable for multimode fiber communications.



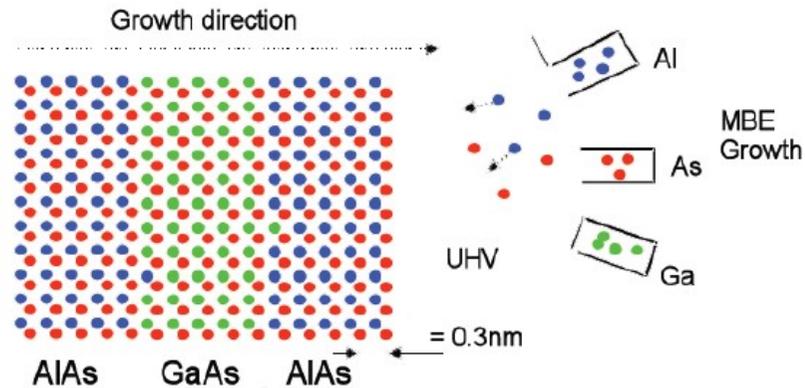
# Epitaxial growth technology

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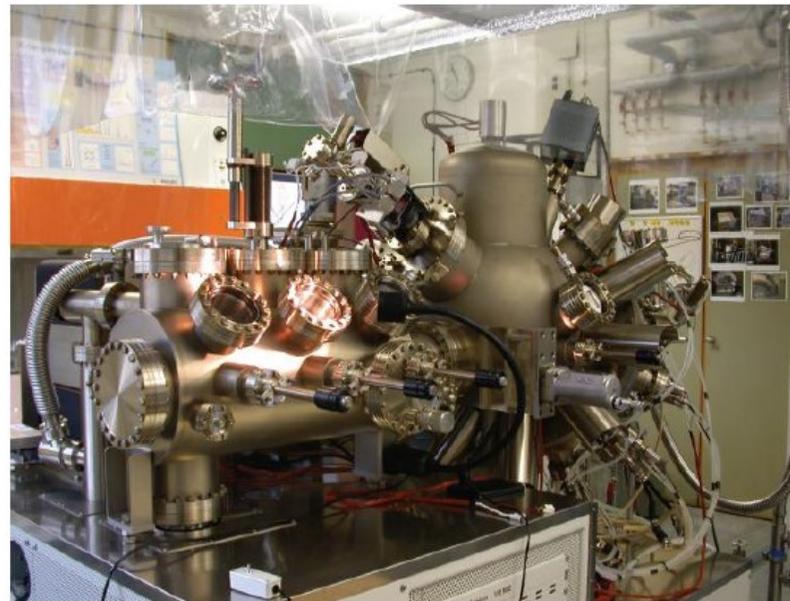
- Heterostructures are grown **epitaxially**, as lattice-matched layers of one semiconductor material over another, by
- molecular-beam epitaxy (MBE) uses **molecular beams** of the constituent elements in a high-vacuum environment,
  - liquid-phase epitaxy (LPE) uses the **cooling of a saturated solution** containing the constituents in contact with the substrate (but layers are thick)
  - vapor-phase epitaxy (VPE) and metal-organic chemical vapor deposition (MOCVD) use **gases in a reactor**.

The performance of early laser diode was limited by manufacturing techniques





MBE growth reactor

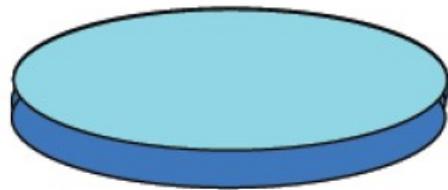


The compositions and dopings of the individual layers are determined by **manipulating the arrival rates** of the molecules and the **temperature** of the substrate surface.

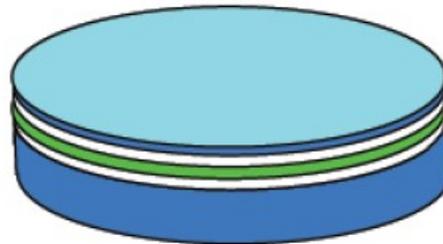
Individual layers can be made very thin (atomic layer accuracy)

# Fabrication techniques

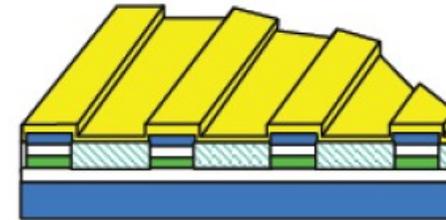
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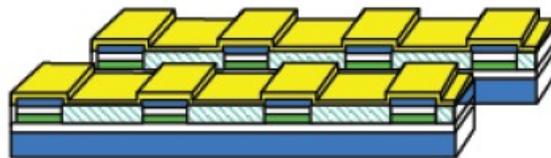
1- SUBSTRATE



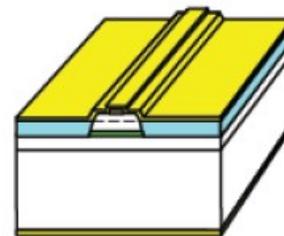
2- EPITAXIE



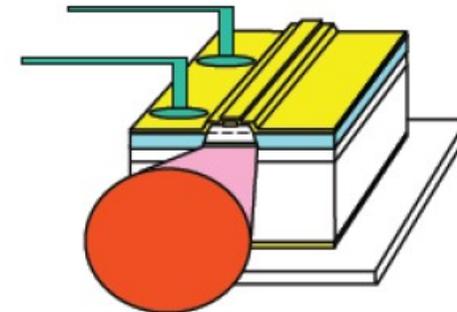
3- LASER PROCESSING



4- FACETS CLEAVING

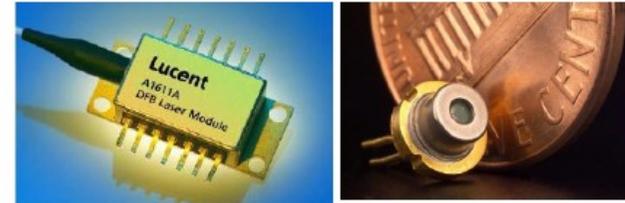


5- SINGLE CHIP  
PREPARATION



6- MOUNTING, BONDING

- Packaging allows **integrating laser diodes in devices**
  - Mechanical and optical coupling to an optical fiber
  - Temperature stabilization
  - Photodiode for monitoring of the optical power, with respect to pump current level.
  - Optical Isolation (avoid back reflections from the fiber)
- But: significantly **increases the fabrication cost.**



A laser diode with the case cut away. The laser diode chip is the small black chip at the front; a photodiode at the back is used to control output power.

**Laser diode:** just the laser; **diode laser:** the complete system

